

EUROPEAN PATENT OFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER : 11144527
PUBLICATION DATE : 28-05-99

APPLICATION DATE : 06-11-97
APPLICATION NUMBER : 09304197

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INT.CL. : H01B 1/22 C08L 63/00 C09J163/00 H05K 3/32

TITLE : ELECTRONIC PARTS BONDING CONDUCTIVE PASTE

ABSTRACT : PROBLEM TO BE SOLVED: To provide an electronic-parts-bonding conductive paste capable of inhibiting the migration of silver ion.

SOLUTION: An electronic-parts-bonding conductive paste containing an epoxy resin, silver powders serving as conductive particles, a hardening agent, and a diluent is mixed with a silver ion bonding agent which forms complex with silver ions ionized in high moisture. As the silver ion bonding agent, 2,4- diamino-6-vnyl-S-triazine isocyanuric acid adduct or 2,4-diamino-6- methacryloiloxyethyl-S-triazine isocyanuric acid adduct is used.

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